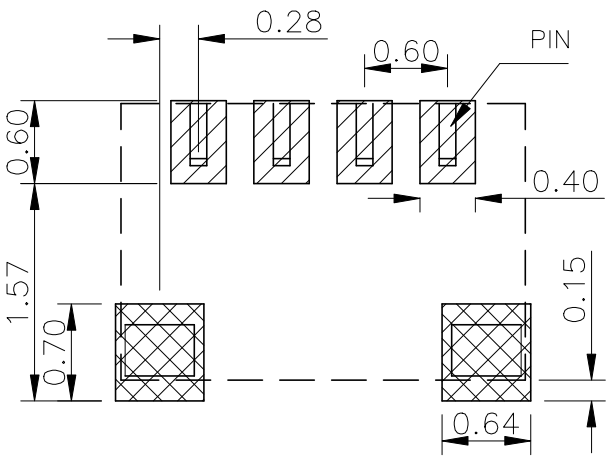
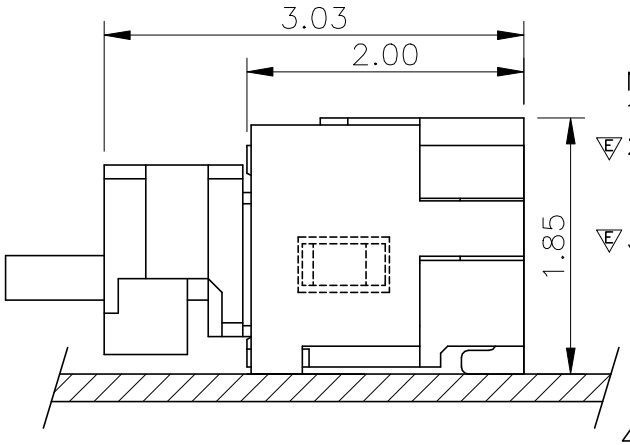
| REV. | ECN NO. | DESCRIPTION | DATE | DESIGN |
|---|---|---|---|---|
| E | | 调整电气性能描述&更新图框 | 2021.10.18 | XUETAOGUO |
| | | | | |




RECCOMENDED PCB LAYOUT

DEFAULT TOL:±0.05




NOTE:

1.MATERIAL: SEE BOM

E 2.FINISH: CONTACT: 50U"MIN,NICKEL UNDERPLATING OVERALL. SURFACE FOLLOW THE P/N.

E 3. SPEC. PLS. REFER TO EI002:

DIM. MARKED (XX) SHOULD BE MEASURED BY FAI;

. DIM. MARKED ▽ SHOULD BE CONTROLLED BY QC;

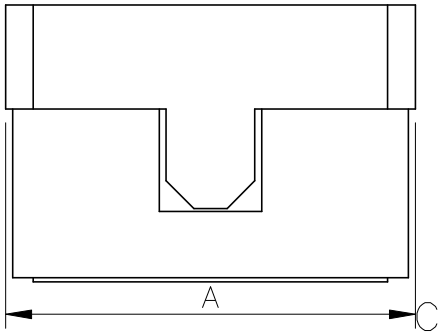
. DIM. MARKED (M) SHOULD BE MEASURED TERMLY BY QC;

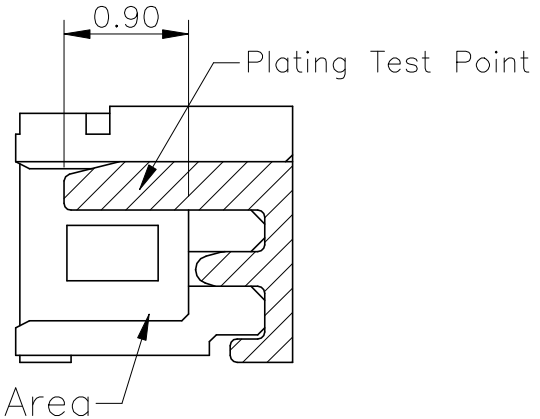
. DIM. MARKED (CPK) SHOULD BE ANALYSED TERMLY BY QC;

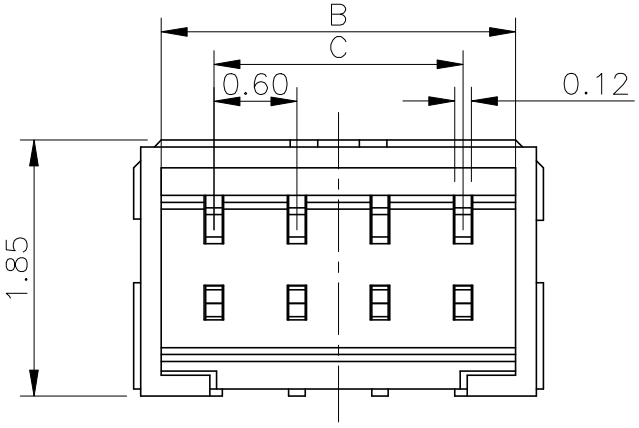
4.ORDERING INFORMATION:

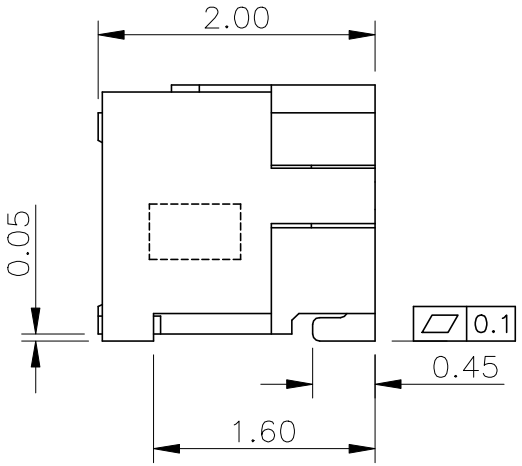
WB0614 H- XX X X X

- X: B:BLACK, N:NATURAL
- X: PLATING SPEC — S:BRIGHT TIN100u", MIN; G:GOLD FLASH; T:GOLD 3U" on contact area
- XX: PIN NO.
- X: PACKING: 0:TAPE&REEL; 1:TUBE
- H: WITHOUT "H" : WITH HALOGEN; WITH "H" : HALOGEN FREE




| CIRCUITS | DIMENSION | | |
|---|---|---|---|
| | A | B | C |
| 4 | 2.96 | 2.56 | 1.80 |
| 6 | 4.16 | 3.76 | 3.00 |

| NO. | DESCRIPTION | Q'TY. | MATERIAL |
|---|---|---|---|
| 3 | NIAL | 2 | Copper Alloy |
| 2 | TERMINAL | ~ | Copper Alloy |
| 1 | HOUSING | 1 | THERMALPLASTIC,UL94-V0 NATURAL |

一般公差
TOLERANCES
X. ±0.5 .XX ±0.15
.X ±0.25 .XXX ±0.10
ANGLES ±2°

希尔盛精密电子(昆山)有限公司

檢驗尺寸標示
SYMBOLS (C) AND (M) INDICATE CLASSIFICATION DIMENSION
(C) MARK IS CRITICAL DIM.
(M) MARK IS MAJOR DIM.

品名 (TITLE) 0.6MM PINTCH

圖號 (DWG NO.) C-WB0614H-XXXXX

製圖 (DR) XUETAOGUO

審核 (CHKD) LEO-HE

核准 (APPD) LEO-HE

表面處理 (FINISH)

比例 (SCALE) 5:1

單位 (UNITS) mm

張數 (SHEET) 1/1

SIZE A4

REV E